

MARKED UP VERSION OF THE CLAIM

24. An electronic device comprising a semiconductor device and a circuit board to which said semiconductor device is electrically connected assembled using a thermosetting resin composition according to [any one of Claims 1-23] Claim 1 as an underfill sealant between the semiconductor device and the circuit board, wherein reaction products of the composition are capable of softening and losing their adhesiveness under exposure to temperature conditions in excess of those used to cure the composition.